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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/723,500	11/26/2003	Kendall W. Prince	9002.16	8993
7590 11/30/2005			EXAMINER	
KIRTON & McCONKIE			CHEN, BRET P	
60 East South Temple, Suite 1800 Salt Lake City, UT 84111			ART UNIT	PAPER NUMBER
			1762	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
	10/723,500	PRINCE ET AL.			
Office Action Summary	Examiner	Art Unit			
	B. Chen	1762			
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the d	orrespondence address -			
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tin will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on 06 Se	eptember 2005.				
2a) ☐ This action is <b>FINAL</b> . 2b) ☑ This	This action is <b>FINAL</b> . 2b)⊠ This action is non-final.				
	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is				
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.			
Disposition of Claims					
4) ☐ Claim(s) 1-24 is/are pending in the application. 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-24 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	vn from consideration.				
Application Papers					
9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex	epted or b) objected to by the liderawing(s) be held in abeyance. Section is required if the drawing(s) is object.	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).			
Priority under 35 U.S.C. § 119					
<ul> <li>12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents have been received.</li> <li>2. Certified copies of the priority documents have been received in Application No.</li> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>					
Attachment(s)  1) Notice of References Cited (PTO-892)  2) Notice of Draftsperson's Patent Drawing Review (PTO-948)  3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:				

## **DETAILED ACTION**

Claims 1-24 are pending in this application.

## Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hey et al. (4,987,856). Hey discloses a method of providing a multi station single wafer chemical vapor deposition processor 10 which utilizes a wafer handling apparatus 16 in combination with a lock lock 14 (col.2 lines 5-26). Specifically, a port 12 is utilized to transport wafers into and out of the reactor (col.3 lines 13-30) and is rectangular in shape (see Figure 1). It is the examiner's position that this port meets the limitation of the claimed aperture which conforms to the crosssectional profile of the substrate. However, the reference remains silent on a substantially rigid substrate which has a substantially uniform cross-sectional profile.

It is noted that Hey discloses the use of semiconductor wafers. One skilled in the art would know that semiconductor wafers are generally rigid and have a uniform cross-sectional profile. It would have been obvious to utilize a substrate with a substantially rigid wafer which has a substantially uniform cross-sectional profile with the expectation of obtaining similar results.

In dependent claims 2, 6-11, the applicant requires specific temperature, thickness and composition. One skilled in the art would realize that lower processing temperatures, reduced thicknesses are desirable in a semiconductor wafer. Different compositions can also be utilized to achieve the desired semiconducting properties. It would have been obvious to one having ordinary skill in the art to have determined the optimum value of a cause effective variable such as temperature, thickness and composition through routine experimentation in the absence of a showing of criticality.

The limitations of claims 3-5, 12-13 have been addressed above.

In independent claim 14, the applicant requires a non-continuous substrate. This limitation is met by the semiconductor wafer of Hey.

The limitations of claims 15-24 have been addressed above.

Claims 1-24 are rejected under 35 U.S.C. 103(a) as being unpatentable over

Toshima (4,785,962). Toshima discloses a method of using access openings to semiconductor vacuum fabrication chambers by using a slit valve (col.1 lines 5-13). Specifically, a multiple chamber system 10 has a vacuum loadlock chamber 11 which mounts several single wafer processing chambers 12, 13, 14, and 15 which contain standard plastic cassettes (col.2 line 65 – col.3 line 10). A small elongated slit or slot 42-46 to provide access between processing chambers 12-15 and loadlock chamber 11 are utilized (col.3 lines 25-46 and Figures 1-3). It is the examiner's position that this slot meets the limitation of the claimed aperture which conforms to the cross-sectional profile of the substrate. However, the reference remains silent on applying a coating.

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It is noted that the reference clearly teaches of processing in a vacuum fabrication chamber. One well known process is coating. It would have been obvious to utilize a coating step as the processing step with the expectation of obtaining a processed semiconductor wafer.

The limitations of claims 3-24 have been addressed above.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to B. Chen whose telephone number is (571) 272-1417. The examiner can normally be reached on 7:30am - 4:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Timothy Meeks can be reached on (571) 272-1423. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Bc 11/28/05

BRET CHEN
PRIMARY EXAMINER